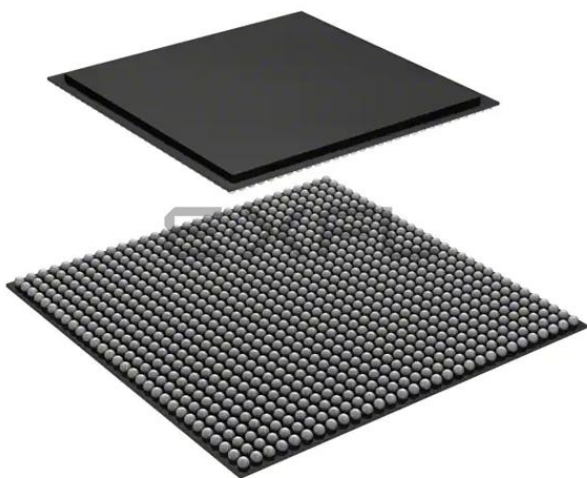




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	8500
Number of Logic Elements/Cells	68000
Total RAM Bits	1056768
Number of I/O	583
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-70e-7f900c

Features

■ High Logic Density for System Integration

- 6K to 95K LUTs
- 90 to 583 I/Os

■ Embedded SERDES (LatticeECP2M Only)

- Data Rates 250 Mbps to 3.125 Gbps
- Up to 16 channels per device
PCI Express, Ethernet (1GbE, SGMII), OBSAI, CPRI and Serial RapidIO.

■ sysDSP™ Block

- 3 to 42 blocks for high performance multiply and accumulate
- Each block supports
 - One 36x36, four 18x18 or eight 9x9 multipliers

■ Flexible Memory Resources

- 55Kbits to 5308Kbits sysMEM™ Embedded Block RAM (EBR)
 - 18Kbit block
 - Single, pseudo dual and true dual port
 - Byte Enable Mode support
- 12K to 202Kbits distributed RAM
 - Single port and pseudo dual port

■ sysCLOCK Analog PLLs and DLLs

- Two GPLLs and up to six SPLLs per device
 - Clock multiply, divide, phase & delay adjust
 - Dynamic PLL adjustment
- Two general purpose DLLs per device

■ Pre-Engineered Source Synchronous I/O

- DDR registers in I/O cells
- Dedicated gearing logic
- Source synchronous standards support
 - SPI4.2, SFI4 (DDR Mode), XGMII
 - High Speed ADC/DAC devices
- Dedicated DDR and DDR2 memory support
 - DDR1: 400 (200MHz) / DDR2: 533 (266MHz)
- Dedicated DQS support

■ Programmable sysI/O™ Buffer Supports Wide Range Of Interfaces

- LVTTTL and LVCMOS 33/25/18/15/12
- SSTL 3/2/18 I, II
- HSTL15 I and HSTL18 I, II
- PCI and Differential HSTL, SSTL
- LVDS, RSDS, Bus-LVDS, MLVDS, LVPECL

■ Flexible Device Configuration

- 1149.1 Boundary Scan compliant
- Dedicated bank for configuration I/Os
- SPI boot flash interface
- Dual boot images supported
- TransFR™ I/O for simple field updates
- Soft Error Detect macro embedded

■ Optional Bitstream Encryption (LatticeECP2/M “S” Versions Only)

■ System Level Support

- ispTRACY™ internal logic analyzer capability
- On-chip oscillator for initialization & general use
- 1.2V power supply

Table 1-1. LatticeECP2 (Including “S-Series”) Family Selection

Device	ECP2-6	ECP2-12	ECP2-20	ECP2-35	ECP2-50	ECP2-70
LUTs (K)	6	12	21	32	48	68
Distributed RAM (Kbits)	12	24	42	64	96	136
EBR SRAM (Kbits)	55	221	276	332	387	1032
EBR SRAM Blocks	3	12	15	18	21	60
sysDSP Blocks	3	6	7	8	18	22
18x18 Multipliers	12	24	28	32	72	88
GPLL + SPLL + DLL	2+0+2	2+0+2	2+0+2	2+0+2	2+2+2	2+4+2
Maximum Available I/O	190	297	402	450	500	583
Packages and I/O Combinations						
144-pin TQFP (20 x 20 mm)	90	93				
208-pin PQFP (28 x 28 mm)		131	131			
256-ball fpBGA (17 x 17 mm)	190	193	193			
484-ball fpBGA (23 x 23 mm)		297	331	331	339	
672-ball fpBGA (27 x 27 mm)			402	450	500	500
900-ball fpBGA (31 x 31 mm)						583

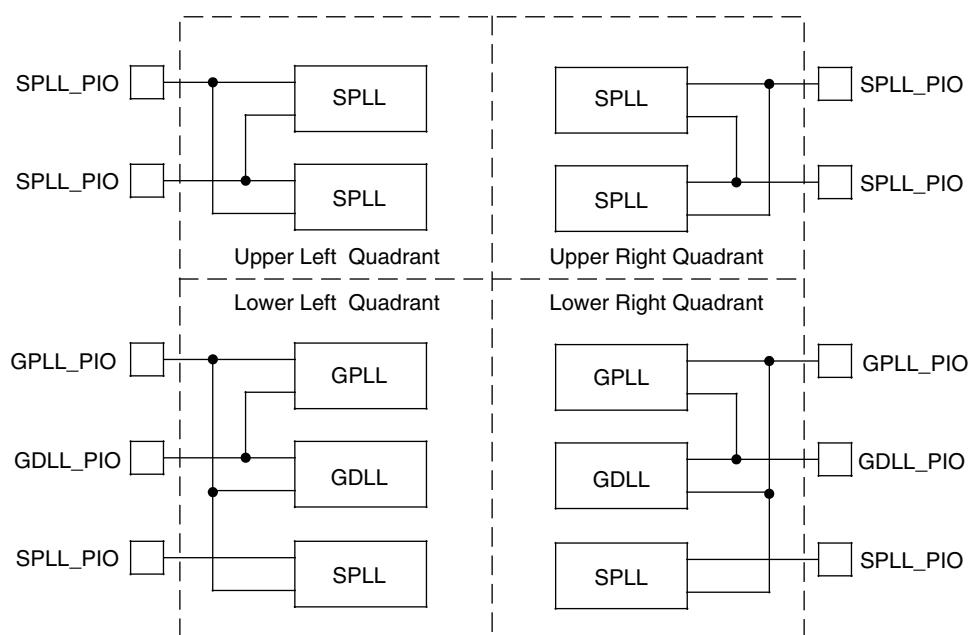
The DLLs in the LatticeECP2/M are used to shift the clock in relation to the data for source synchronous inputs. PLLs are used for frequency synthesis and clock generation for source synchronous interfaces. Cascading PLL and DLL blocks allows applications to utilize the unique benefits of both DLLs and PLLs.

For further information about the DLL, please see the list of additional technical documentation at the end of this data sheet.

GPLL/SPLL/GDLL PIO Input Pin Connections (LatticeECP2M Family Only)

All LatticeECP2M devices contain two GDLLs, two GPLLs and six SPLLs, arranged in quadrants as shown in Figure 2-8. In the LatticeECP2M devices GPLLs, SPLLs and GDLLs share their input pins. Figure 2-8 shows the sharing of SPLLs input pin connections in the upper two quadrants and the sharing of GDLL, GPLL and SPLL input pin connections in the lower two quadrants.

Figure 2-8. Sharing of PIO Pins by GPLL, SPLL and GDLL in LatticeECP2M Devices



Clock Dividers

LatticeECP2/M devices have two clock dividers, one on the left side and one on the right side of the device. These are intended to generate a slower-speed system clock from a high-speed edge clock. The block operates in a $\div 2$, $\div 4$ or $\div 8$ mode and maintains a known phase relationship between the divided down clock and the high-speed clock based on the release of its reset signal. The clock dividers can be fed from selected PLL/DLL outputs, DLL-DELA delay blocks, routing or from an external clock input. The clock divider outputs serve as primary clock sources and feed into the clock distribution network. The Reset (RST) control signal resets input and synchronously forces all outputs to low. The RELEASE signal releases outputs synchronously to the input clock. For further information about clock dividers, please see the list of additional technical documentation at the end of this data sheet. Figure 2-9 shows the clock divider connections.

this special vertical routing channel and the eight secondary clock regions for the ECP2-50. LatticeECP2 devices have four secondary clocks (SC0 to SC3) which are distributed to every region.

The secondary clock muxes are located in the center of the device. Figure 2-16 shows the mux structure of the secondary clock routing. Secondary clocks SC0 to SC3 are used for clock and control and SC4 to SC7 are used for high fan-out signals.

Figure 2-15. Secondary Clock Regions ECP2-50

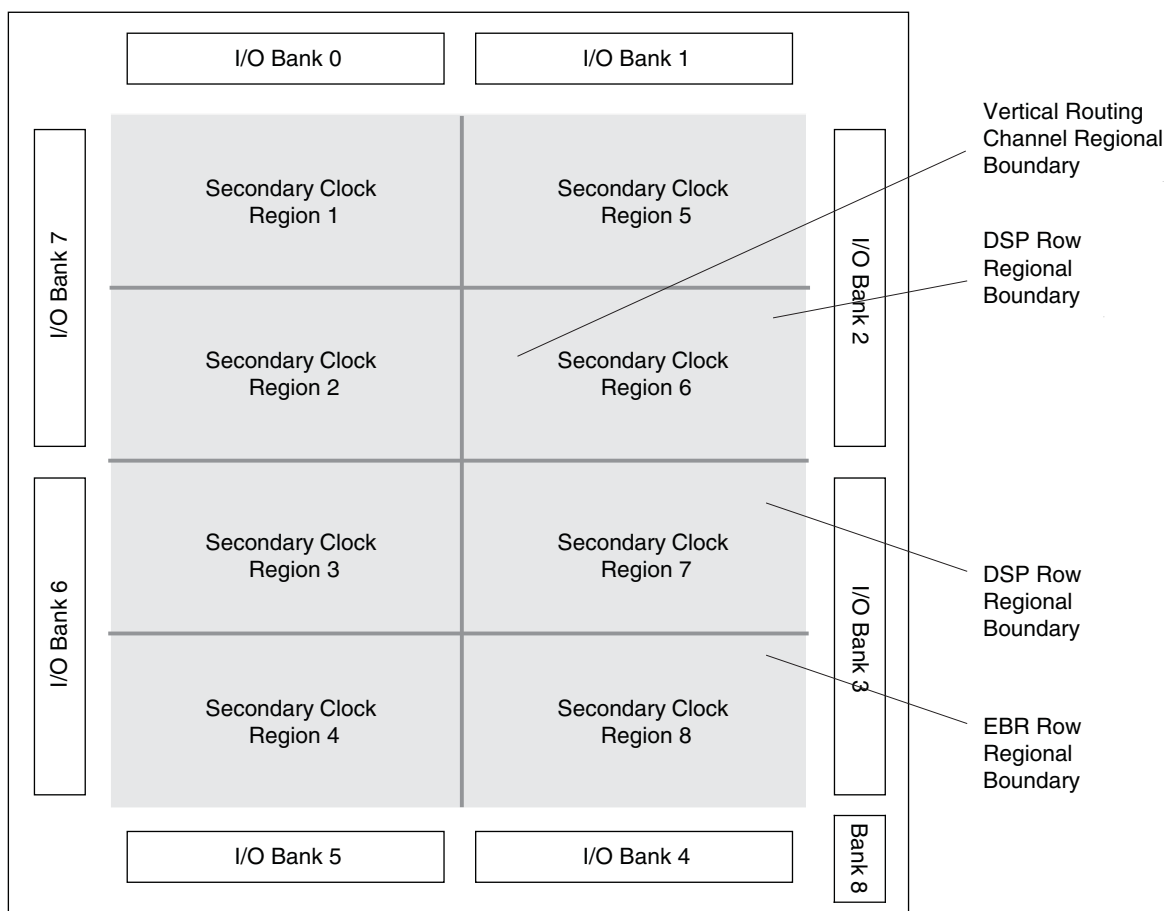
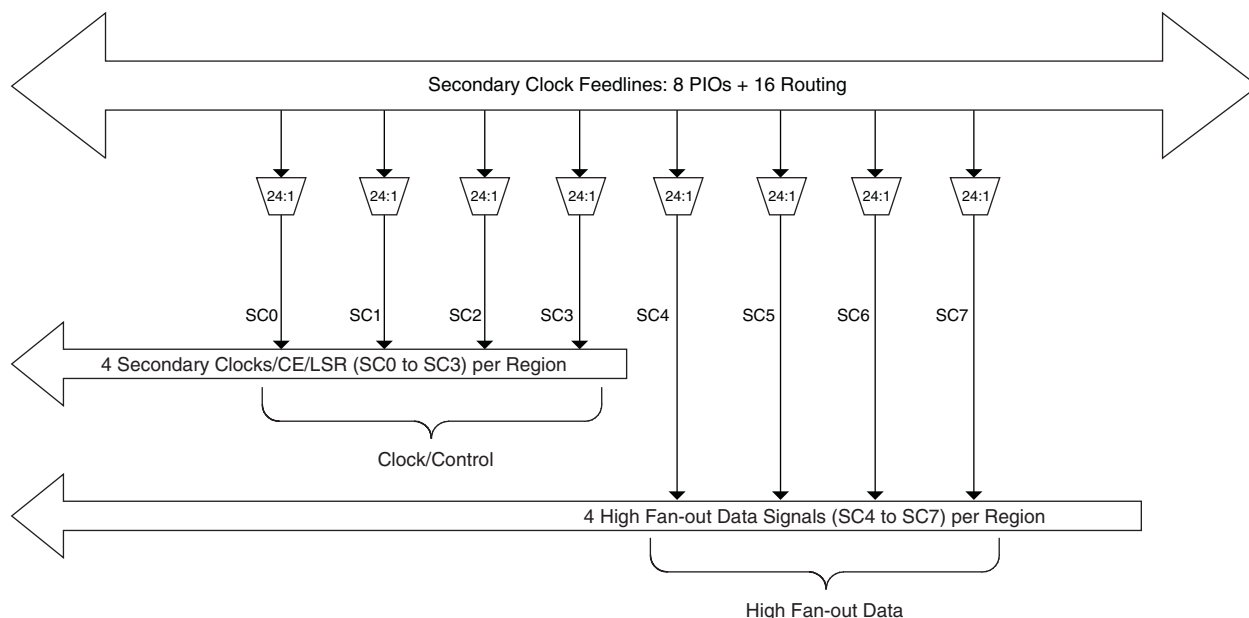


Figure 2-16. Secondary Clock Selection

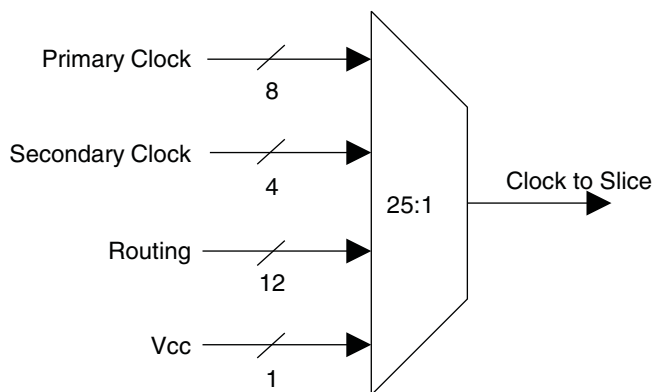


Slice Clock Selection

Figure 2-17 shows the clock selections and Figure 2-18 shows the control selections for Slice0 through Slice2. All the primary clocks and the four secondary clocks are routed to this clock selection mux. Other signals can be used as a clock input to the slices via routing. Slice controls are generated from the secondary clocks or other signals connected via routing.

If none of the signals are selected for both clock and control then the default value of the mux output is 1. Slice 3 does not have any registers; therefore it does not have the clock or control muxes.

Figure 2-17. Slice0 through Slice2 Clock Selection



LatticeECP2/M DSP Performance

Table 2-11 lists the maximum performance in millions of MAC operations per second (MMAC) for each member of the LatticeECP2/M family.

Table 2-11. DSP Performance

Device	DSP Block	DSP Performance GMAC
ECP2-6	3	3.9
ECP2-12	6	7.8
ECP2-20	7	9.1
ECP2-35	8	10.4
ECP2-50	18	23.4
ECP2-70	22	28.6
ECP2M20	6	7.8
ECP2M35	8	10.4
ECP2M50	22	28.6
ECP2M70	24	31.2
ECP2M100	42	54.6

For further information about the sysDSP block, please see the list of additional technical information at the end of this data sheet.

Programmable I/O Cells (PIC)

Each PIC contains two PIOs connected to their respective sysI/O buffers as shown in Figure 2-28. The PIO Block supplies the output data (DO) and the tri-state control signal (TO) to the sysI/O buffer and receives input from the buffer. Table 2-12 provides the PIO signal list.

SERDES Power Supply Requirements (LatticeECP2M Family Only)¹

Over Recommended Operating Conditions

Symbol	Description	Typ. ²	Units
Standby (Power Down)			
I _{CCTX-SB}	V _{CCTX} current (per channel)	10	μA
I _{CCR_X-SB}	V _{CCR_X} current (per channel)	75	μA
I _{CCIB-SB}	Input buffer current (per channel)	0	μA
I _{CCOB-SB}	Output buffer current (per channel)	0	μA
I _{CCP-SB}	SERDES PLL current (per quad)	30	μA
I _{CCAX33-SB}	SERDES termination current (per quad)	10	μA
Operating (Data Rate = 3.125 Gbps)			
I _{CCTX-OP}	V _{CCTX} current (per channel)	19	mA
I _{CCR_X-OP}	V _{CCR_X} current (per channel)	34	mA
I _{CCIB-OP}	Input buffer current (per channel)	4	mA
I _{CCOB-OP}	Output buffer current (per channel)	13	mA
I _{CCP-OP}	SERDES PLL current (per quad)	26	mA
I _{CCAX33-OP}	SERDES termination current (per quad)	0.01	mA

1. Equalization enabled, pre-emphasis disabled.

2. T_J = 25°C, power supplies at nominal voltage.

SERDES Power (LatticeECP2M Family Only)

Table 3-1 presents the SERDES power for one channel.

Table 3-1. SERDES Power¹

Symbol	Description	Typ. ²	Units
P _{S-1CH-31}	SERDES power (one channel @ 3.125 Gbps)	90	mW
P _{S-1CH-25}	SERDES power (one channel @ 2.5 Gbps)	87	mW
P _{S-1CH-12}	SERDES power (one channel @ 1.25 Gbps)	86	mW
P _{S-1CH-02}	SERDES power (one channel @ 250 Mbps)	76	mW

1. One quarter of the total quad power (includes contribution from common circuits, all channels in the quad operating, pre-emphasis disabled, equalization enabled).

2. Typical values measured at 25°C and 1.2V.

LatticeECP2/M External Switching Characteristics⁹ (Continued)

Over Recommended Operating Conditions

Parameter	Description	Device	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t _{DIBSPI}	Data Invalid Before Clock (Transmit)	ECP2-20	—	280	—	280	—	280	ps
		ECP2-35	—	280	—	280	—	280	ps
		ECP2-50	—	280	—	280	—	280	ps
		ECP2-70	—	280	—	280	—	280	ps
		ECP2M20	—	230	—	230	—	230	ps
		ECP2M35	—	230	—	230	—	230	ps
		ECP2M50	—	230	—	230	—	230	ps
		ECP2M70	—	230	—	230	—	230	ps
		ECP2M100	—	230	—	230	—	230	ps
XGMII I/O Pin Parameters (312 Mbps) ⁵									
t _{SUXGMII}	Data Setup Before Read Clock	ECP2/M	480	—	480	—	480	—	ps
t _{HXGMII}	Data Hold After Read Clock	ECP2/M	480	—	480	—	480	—	ps
t _{DVBCKXGMII}	Data Valid Before Clock	ECP2/M	960	—	960	—	960	—	ps
t _{DVACKXGMII}	Data Valid After Clock	ECP2/M	960	—	960	—	960	—	ps
Primary									
f _{MAX_PRI} ⁷	Frequency for Primary Clock Tree	ECP2/M	—	420	—	357	—	311	MHz
t _{W_PRI}	Clock Pulse Width for Primary Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t _{SKEW_PRI}	Primary Clock Skew Within a Bank	ECP2/M	—	300	—	360	—	420	ps
Edge Clock									
f _{MAX_EDGE} ⁷	Frequency for Edge Clock	ECP2/M	—	420	—	357	—	311	MHz
t _{W_EDGE}	Clock Pulse Width for Edge Clock	ECP2/M	0.95	—	1.19	—	2.00	—	ns
t _{SKEW_EDGE}	Edge Clock Skew Within an Edge of the Device	ECP2/M	—	300	—	360	—	420	ps

- General timing numbers based on LVCMOS 2.5, 12mA, 0pf load.
- DDR timing numbers based on SSTL25 for BGA packages only.
- DDR2 timing numbers based on SSTL18 for BGA packages only.
- SPI4.2 and SFI4 timing numbers based on LVDS25 for BGA packages only.
- XGMII timing numbers based on HSTL class I. A corresponding left/right dedicated clock buffer is used when using the SPI4.2 interface to the left or right edge of the device. For SPI4.2 mode, the software tool will help in selecting the appropriate clock buffer.
- IP will be used to support DDR and DDR2 memory data rates down to 95MHz. This approach uses a free-running clock and PFU register to sample the data instead of the hardwired DDR memory interface.
- Using the LVDS I/O standard.
- ECP2-6 and ECP2-12 do not support SPI4.2
- The AC numbers do not apply to PCLK6 and PCLK7.
- Applies to CLKOP only.
- Please refer to TN1159, [LatticeECP2/M Pin Assignment Recommendations](#) for best performance.

LatticeECP2/M Family Timing Adders^{1, 2, 3} (Continued)
Over Recommended Operating Conditions

Buffer Type	Description	-7	-6	-5	Units
LVC MOS25_4mA	LVC MOS 2.5 4mA drive, slow slew rate	2.18	2.26	2.33	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive, slow slew rate	2.19	2.35	2.51	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive, slow slew rate	1.50	1.66	1.82	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive, slow slew rate	1.60	1.59	1.58	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive, slow slew rate	1.43	1.39	1.34	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive, slow slew rate	2.22	2.27	2.32	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive, slow slew rate	1.93	2.08	2.23	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive, slow slew rate	1.43	1.51	1.58	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive, slow slew rate	1.47	1.46	1.45	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive, slow slew rate	2.32	2.38	2.43	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive, slow slew rate	1.84	1.98	2.12	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive, slow slew rate	2.52	2.63	2.74	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive, slow slew rate	1.69	1.83	1.96	ns
PCI33	PCI33	0.04	0.04	0.04	ns

1. Timing Adders are characterized but not tested on every device.

2. LVC MOS timing measured with the load specified in Switching Test Condition table.

3. All other standards tested according to the appropriate specifications.

4. These timing adders are measured with the recommended resistor values.

Timing v.A 0.11

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP (Cont.)

LFE2-12E/SE					LFE2-20E/SE				
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential	
92	PB44A	4	BDQ42	T	PB54A	4	BDQ51	T	
93	VCCIO4	4			VCCIO4	4			
94	PB44B	4	BDQ42	C	PB54B	4	BDQ51	C	
95	PB48A	4	BDQ51	T	PB58A	4	BDQ60	T	
96	PB48B	4	BDQ51	C	PB58B	4	BDQ60	C	
97	VCC	-			VCC	-			
98	PB52A	4	BDQ51	T	PB60A	4	BDQS60	T	
99	PB52B	4	BDQ51	C	PB60B	4	BDQ60	C	
100	VCCIO4	4			VCCIO4	4			
101	PB54A	4	BDQ51		PB63A	4	BDQ60		
102	GND	-			GND	-			
103	PB55A	4	VREF2_4/BDQ51	T	PB64A	4	VREF2_4/BDQ60	T	
104	PB55B	4	VREF1_4/BDQ51	C	PB64B	4	VREF1_4/BDQ60	C	
105	CFG1	8			CFG1	8			
106	PROGRAMN	8			PROGRAMN	8			
107	CFG2	8			CFG2	8			
108	INITN	8			INITN	8			
109	CFG0	8			CFG0	8			
110	CCLK	8			CCLK	8			
111	DONE	8			DONE	8			
112	PR29A	8	D0/SPIFASTN		PR43A	8	D0/SPIFASTN		
113	VCCIO8	8			VCCIO8	8			
114	PR26A	8	D6		PR40A	8	D6		
115	GND	-			GND	-			
116	VCC	-			VCC	-			
117	PR25B	8	D7/SPID0	C	PR39B	8	D7/SPID0	C	
118	VCCIO8	8			VCCIO8	8			
119	PR25A	8	DI/CSSPI0N	T	PR39A	8	DI/CSSPI0N	T	
120	PR24B	8	DOUT/CSON	C	PR38B	8	DOUT/CSON	C	
121	PR24A	8	BUSY/SISPI	T	PR38A	8	BUSY/SISPI	T	
122	GND	-			GND	-			
123	VCCIO3	3			VCCIO3	3			
124	PR21A	3	RLM0_GPLLT_FB_A		PR31A	3	RLM0_GPLLT_FB_A/RDQ34		
125	VCCAUX	-			VCCAUX	-			
126	PR20B	3	RLM0_GPLL_C_IN_A**	C (LVDS)*	PR30B	3	RLM0_GPLL_C_IN_A**/RDQ34	C (LVDS)*	
127	PR20A	3	RLM0_GPLL_T_IN_A**	T (LVDS)*	PR30A	3	RLM0_GPLL_T_IN_A**/RDQ34	T (LVDS)*	
128	RLM0_PLLCAP	3			RLM0_PLLCAP	3			
129	VCC	-			VCC	-			
130	PR18B	3	RLM0_GDLL_C_FB_A	C	PR28B	3	RLM0_GDLL_C_FB_A/RDQ25	C	
131	PR18A	3	RLM0_GDLL_T_FB_A	T	PR28A	3	RLM0_GDLL_T_FB_A/RDQ25	T	
132	PR17B	3	RLM0_GDLL_C_IN_A**	C (LVDS)*	PR27B	3	RLM0_GDLL_C_IN_A**/RDQ25	C (LVDS)*	
133	PR17A	3	RLM0_GDLL_T_IN_A**	T (LVDS)*	PR27A	3	RLM0_GDLL_T_IN_A**/RDQ25	T (LVDS)*	
134	PR16B	3	VREF2_3	C	PR22B	3	VREF2_3/RDQ25	C	
135	VCCIO3	3			VCCIO3	3			
136	PR16A	3	VREF1_3	T	PR22A	3	VREF1_3/RDQ25	T	
137	PR15B	3	PCLKC3_0	C (LVDS)*	PR21B	3	PCLKC3_0/RDQ25	C (LVDS)*	

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP (Cont.)

LFE2-12E/SE					LFE2-20E/SE				
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential	
184	GND	-			GND	-			
185	PT28A	0	PCLKT0_0	T	PT37A	0	PCLKT0_0	T	
186	PT26B	0		C	PT36B	0		C	
187	PT26A	0		T	PT36A	0		T	
188	VCC	-			VCC	-			
189	PT20B	0		C	PT30B	0		C	
190	VCCAUX	-			VCCAUX	-			
191	PT20A	0		T	PT30A	0		T	
192	GND	-			GND	-			
193	PT18B	0		C	PT26B	0		C	
194	PT18A	0		T	PT26A	0		T	
195	VCCIO0	0			VCCIO0	0			
196	PT16B	0		C	PT20B	0		C	
197	PT16A	0		T	PT20A	0		T	
198	VCC	-			VCC	-			
199	PT12B	0		C	PT12B	0		C	
200	PT12A	0		T	PT12A	0		T	
201	GND	-			GND	-			
202	PT8B	0		C	PT8B	0		C	
203	PT8A	0		T	PT8A	0		T	
204	PT6B	0		C	PT6B	0		C	
205	PT6A	0		T	PT6A	0		T	
206	VCCIO0	0			VCCIO0	0			
207	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C	
208	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T	

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-20E/SE Logic Signal Connections: 256 fpBGA

LFE2-20E/SE					
Ball Number	Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
C3	C3	PL2A	7	VREF2_7	T (LVDS)*
C2	C2	PL2B	7	VREF1_7	C (LVDS)*
VCCIO	VCCIO	VCCIO7	7		
-	GND	GNDIO7	7		
D3	D3	PL7A	7	LDQ8	T
D4	D4	PL6A	7	LDQ8	T (LVDS)*
D2	D2	PL7B	7	LDQ8	C
GND	GND	GNDIO7	-		
E4	E4	PL6B	7	LDQ8	C (LVDS)*
B1	B1	PL13A	7	LDQ16	T
C1	C1	PL13B	7	LDQ16	C
F5	F5	PL15A	7	LDQ16	T
VCCIO	VCC	VCCIO	7		
F4	F4	PL14A	7	LDQ16	T (LVDS)*
G6	G6	PL15B	7	LDQ16	C
G4	G4	PL14B	7	LDQ16	C (LVDS)*
D1	D1	PL16A	7	LDQS16	T (LVDS)*
GND	GND	GNDIO7	-		
E1	E1	PL16B	7	LDQ16	C (LVDS)*
F3	F3	PL17A	7	LDQ16	T
G3	G3	PL17B	7	LDQ16	C
VCCIO	VCCIO	VCCIO7	7		
F2	F2	PL18A	7	LDQ16	T (LVDS)*
F1	F1	PL18B	7	LDQ16	C (LVDS)*
GND	GND	GNDIO7	-		
G2	G2	PL19A	7	PCLKT7_0/LDQ16	T
G1	G1	PL19B	7	PCLKC7_0/LDQ16	C
H6	H6	PL21A	6	PCLKT6_0/LDQ25	T (LVDS)*
VCCIO	VCCIO	VCCIO6	6		
H5	H5	PL21B	6	PCLKC6_0/LDQ25	C (LVDS)*
H4	H4	PL22A	6	VREF2_6/LDQ25	T
GND	GND	GNDIO6	-		
H3	H3	PL22B	6	VREF1_6/LDQ25	C
H2	H2	PL27A	6	LLM0_GDLLT_IN_A**/LDQ25	T (LVDS)*
H1	H1	PL27B	6	LLM0_GDLLC_IN_A**/LDQ25	C (LVDS)*
G10	G10	VCC	-		
J4	J4	PL28A	6	LLM0_GDLLT_FB_A/LDQ25	T
J5	J5	PL28B	6	LLM0_GDLLC_FB_A/LDQ25	C
J6	J6	LLM0_PLLCAP	6		
K4	K4	PL30A	6	LLM0_GPLLT_IN_A**/LDQ34	T (LVDS)*
GND	GND	GNDIO6	-		

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
A6	PT21A	0		T	PT30A	0		T	
GNDIO	GNDIO0	-			GNDIO0	-			
C7	PT17B	0		C	PT26B	0		C	
D10	PT18B	0		C	PT27B	0		C	
C6	PT17A	0		T	PT26A	0		T	
E10	PT18A	0		T	PT27A	0		T	
VCCIO	VCCIO0	0			VCCIO0	0			
F10	PT15B	0		C	PT24B	0		C	
B6	PT16B	0		C	PT25B	0		C	
D9	PT15A	0		T	PT24A	0		T	
B5	PT16A	0		T	PT25A	0		T	
GNDIO	GNDIO0	-			GNDIO0	-			
A5	PT13B	0		C	PT22B	0		C	
F9	PT14B	0		C	PT23B	0		C	
A4	PT13A	0		T	PT22A	0		T	
E9	PT14A	0		T	PT23A	0		T	
VCCIO	VCCIO0	0			VCCIO0	0			
G8	PT11B	0		C	PT20B	0		C	
A3	PT12B	0		C	PT21B	0		C	
E8	PT11A	0		T	PT20A	0		T	
A2	PT12A	0		T	PT21A	0		T	
GNDIO	GNDIO0	-			GNDIO0	-			
-	-	-			VCCIO0	0			
C3	PT10B	0		C	PT10B	0		C	
B3	PT10A	0		T	PT10A	0		T	
-	-	-			GNDIO0	-			
E7	PT8B	0		C	PT8B	0		C	
F8	PT9B	0		C	PT9B	0		C	
F7	PT8A	0		T	PT8A	0		T	
D7	PT9A	0		T	PT9A	0		T	
VCCIO	VCCIO0	0			VCCIO0	0			
D4	PT6B	0		C	PT6B	0		C	
D5	PT7B	0		C	PT7B	0		C	
C4	PT6A	0		T	PT6A	0		T	
D6	PT7A	0		T	PT7A	0		T	
GNDIO	GNDIO0	-			GNDIO	-			
J7	PT4B	0		C	PT4B	0		C	
B2	PT5B	0		C	PT5B	0		C	
H7	PT4A	0		T	PT4A	0		T	
B1	PT5A	0		T	PT5A	0		T	
VCCIO	VCCIO0	0			VCCIO0	0			
D1	PT2B	0	VREF2_0	C	PT2B	0	VREF2_0	C	
D3	PT3B	0		C	PT3B	0		C	
C1	PT2A	0	VREF1_0	T	PT2A	0	VREF1_0	T	

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
W20	CFG0	8			CFG0	8		
V20	PROGRAMN	8			PROGRAMN	8		
W22	CCLK	8			CCLK	8		
V22	INITN	8			INITN	8		
V21	DONE	8			DONE	8		
GNDIO	GNDIO8	-			GNDIO8	-		
R16	PR58B	8	WRITEN	C	PR77B	8	WRITEN	C
R17	PR58A	8	CS1N	T	PR77A	8	CS1N	T
U19	PR57B	8	CSN	C	PR76B	8	CSN	C
U20	PR57A	8	D0/SPIFASTN	T	PR76A	8	D0/SPIFASTN	T
VCCIO	VCCIO8	8			VCCIO	8		
U22	PR56B	8	D1	C	PR75B	8	D1	C
U21	PR56A	8	D2	T	PR75A	8	D2	T
T20	PR55B	8	D3	C	PR74B	8	D3	C
GNDIO	GNDIO8	-			GNDIO8	-		
T19	PR55A	8	D4	T	PR74A	8	D4	T
T17	PR54B	8	D5	C	PR73B	8	D5	C
T18	PR54A	8	D6	T	PR73A	8	D6	T
T21	PR53B	8	D7/SPID0	C	PR72B	8	D7/SPID0	C
VCCIO	VCCIO8	8			VCCIO	8		
T22	PR53A	8	DI/CSSPION	T	PR72A	8	DI/CSSPION	T
R18	PR52B	8	DOUT/CSON	C	PR71B	8	DOUT/CSON	C
R19	PR52A	8	BUSY/SISPI	T	PR71A	8	BUSY/SISPI	T
GNDIO	GNDIO3	-			GNDIO3	-		
VCCIO	VCCIO3	3			VCCIO	3		
R22	PR47B	3	RDQ48	C	PR66B	3	RDQ67	C
R21	PR47A	3	RDQ48	T	PR66A	3	RDQ67	T
P18	PR46B	3	RDQ48	C (LVDS)*	PR65B	3	RDQ67	C (LVDS)*
P19	PR46A	3	RDQ48	T (LVDS)*	PR65A	3	RDQ67	T (LVDS)*
VCCIO	VCCIO3	3			VCCIO	3		
R20	PR45B	3	RLM0_GPLL_C_FB_A/RDQ48	C	PR64B	3	RLM0_GPLL_C_FB_A/RDQ67	C
P22	PR45A	3	RLM0_GPLL_T_FB_A/RDQ48	T	PR64A	3	RLM0_GPLL_T_FB_A/RDQ67	T
P21	PR44B	3	RLM0_GPLL_C_IN_A**/RDQ48	C (LVDS)*	PR63B	3	RLM0_GPLL_C_IN_A**/RDQ67	C (LVDS)*
N21	PR44A	3	RLM0_GPLL_T_IN_A**/RDQ48	T (LVDS)*	PR63A	3	RLM0_GPLL_T_IN_A**/RDQ67	T (LVDS)*
N17	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
N22	PR42B	3	RLM0_GDLL_C_FB_A/RDQ39	C	PR61B	3	RLM0_GDLL_C_FB_A/RDQ58	C
N20	PR42A	3	RLM0_GDLL_T_FB_A/RDQ39	T	PR61A	3	RLM0_GDLL_T_FB_A/RDQ58	T
GNDIO	GNDIO3	-			GNDIO3	-		
M22	PR41B	3	RLM0_GDLL_C_IN_A**/RDQ39	C (LVDS)*	PR60B	3	RLM0_GDLL_C_IN_A**/RDQ58	C (LVDS)*
M21	PR41A	3	RLM0_GDLL_T_IN_A**/RDQ39	T (LVDS)*	PR60A	3	RLM0_GDLL_T_IN_A**/RDQ58	T (LVDS)*
N19	PR40B	3	RDQ39	C	PR59B	3	RDQ58	C
M19	PR40A	3	RDQ39	T	PR59A	3	RDQ58	T
VCCIO	VCCIO3	3			VCCIO	3		
GNDIO	GNDIO3	-			GNDIO3	-		
L22	PR30B	3	RDQ31	C	PR49B	3	RDQ50	C
K22	PR30A	3	RDQ31	T	PR49A	3	RDQ50	T

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
A2	GND	-			GND	-		
A25	GND	-			GND	-		
AA18	GND	-			GND	-		
AA24	GND	-			GND	-		
AA3	GND	-			GND	-		
AA9	GND	-			GND	-		
AD11	GND	-			GND	-		
AD16	GND	-			GND	-		
AD21	GND	-			GND	-		
AD6	GND	-			GND	-		
AE1	GND	-			GND	-		
AE26	GND	-			GND	-		
AF2	GND	-			GND	-		
AF25	GND	-			GND	-		
B1	GND	-			GND	-		
B26	GND	-			GND	-		
C11	GND	-			GND	-		
C16	GND	-			GND	-		
C21	GND	-			GND	-		
C6	GND	-			GND	-		
F18	GND	-			GND	-		
F24	GND	-			GND	-		
F3	GND	-			GND	-		
F9	GND	-			GND	-		
J13	GND	-			GND	-		
J14	GND	-			GND	-		
J21	GND	-			GND	-		
J6	GND	-			GND	-		
K10	GND	-			GND	-		
K11	GND	-			GND	-		
K13	GND	-			GND	-		
K14	GND	-			GND	-		
K16	GND	-			GND	-		
K17	GND	-			GND	-		
L10	GND	-			GND	-		
L11	GND	-			GND	-		
L16	GND	-			GND	-		
L17	GND	-			GND	-		
L24	GND	-			GND	-		
L3	GND	-			GND	-		
M13	GND	-			GND	-		
M14	GND	-			GND	-		
N10	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N14	GND	-			GND	-		

LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
N15	GND	-			GND	-		
N17	GND	-			GND	-		
P10	GND	-			GND	-		
P12	GND	-			GND	-		
P13	GND	-			GND	-		
P14	GND	-			GND	-		
P15	GND	-			GND	-		
P17	GND	-			GND	-		
R13	GND	-			GND	-		
R14	GND	-			GND	-		
T10	GND	-			GND	-		
T11	GND	-			GND	-		
T16	GND	-			GND	-		
T17	GND	-			GND	-		
T24	GND	-			GND	-		
T3	GND	-			GND	-		
U10	GND	-			GND	-		
U11	GND	-			GND	-		
U13	GND	-			GND	-		
U14	GND	-			GND	-		
U16	GND	-			GND	-		
U17	GND	-			GND	-		
V13	GND	-			GND	-		
V14	GND	-			GND	-		
V21	GND	-			GND	-		
V6	GND	-			GND	-		
M3	NC	-			NC	-		
N6	NC	-			NC	-		
P24	NC	-			NC	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

***Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
AG4	NC	-		
AG8	NC	-		
AH1	NC	-		
AH16	NC	-		
AH2	NC	-		
AH26	NC	-		
AH27	NC	-		
AH29	NC	-		
AH30	NC	-		
AH4	NC	-		
AJ1	NC	-		
AJ2	NC	-		
AJ27	NC	-		
AJ28	NC	-		
AJ29	NC	-		
AJ3	NC	-		
AJ30	NC	-		
AK2	NC	-		
AK27	NC	-		
AK28	NC	-		
AK29	NC	-		
AK3	NC	-		
B1	NC	-		
B2	NC	-		
B3	NC	-		
B30	NC	-		
B4	NC	-		
B5	NC	-		
C1	NC	-		
C2	NC	-		
C29	NC	-		
C30	NC	-		
C4	NC	-		
D13	NC	-		
D18	NC	-		
D23	NC	-		
D28	NC	-		
D29	NC	-		
D3	NC	-		
D30	NC	-		
D4	NC	-		
E25	NC	-		
E26	NC	-		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
A21	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12			
A22	URC_SQ_HDOUTP3	12		T	URC_SQ_HDOUTP3	12		T	
C21	URC_SQ_VCCTX3	12			URC_SQ_VCCTX3	12			
B19	URC_SQ_HDINN3	12		C	URC_SQ_HDINN3	12		C	
B18	URC_SQ_VCCIB3	12			URC_SQ_VCCIB3	12			
A19	URC_SQ_HDINP3	12		T	URC_SQ_HDINP3	12		T	
C18	URC_SQ_VCCRX3	12			URC_SQ_VCCRX3	12			
D23	PT73B	1		C	PT82B	1		C	
GNDIO	GNDIO1	-			GNDIO1	-			
E21	PT73A	1		T	PT82A	1		T	
D26	PT72B	1		C	PT81B	1		C	
E26	PT72A	1		T	PT81A	1		T	
E23	PT71B	1		C	PT80B	1		C	
-	-	-			VCCIO1	1			
G22	PT71A	1		T	PT80A	1		T	
VCCIO	VCCIO1	1			-	-			
D22	PT70B	1		C	PT79B	1		C	
F21	PT70A	1		T	PT79A	1		T	
G18	PT69B	1		C	PT78B	1		C	
H18	PT69A	1		T	PT78A	1		T	
D20	PT68B	1		C	PT77B	1		C	
GNDIO	GNDIO1	-			GNDIO1	-			
D21	PT68A	1		T	PT77A	1		T	
E20	PT67B	1		C	PT76B	1		C	
E19	PT67A	1		T	PT76A	1		T	
D19	PT66B	1		C	PT75B	1		C	
VCCIO	VCCIO1	1			VCCIO1	1			
E18	PT66A	1		T	PT75A	1		T	
D18	PT65B	1		C	PT74B	1		C	
C17	PT65A	1		T	PT74A	1		T	
A17	PT64B	1		C	PT73B	1		C	
B17	PT64A	1		T	PT73A	1		T	
GNDIO	GNDIO1	-			GNDIO1	-			
VCCIO	VCCIO1	1			VCCIO1	1			
J18	NC	-			PT66B	1		C	
J19	NC	-			PT66A	1		T	
H17	NC	-			PT65B	1		C	
J17	NC	-			PT65A	1		T	
F18	NC	-			PT64B	1		C	
F17	NC	-			PT64A	1		T	
-	-	-			GNDIO1	-			
A16	PT54B	1		C	PT63B	1		C	
B16	PT54A	1		T	PT63A	1		T	
G17	PT53B	1		C	PT62B	1		C	
G16	PT53A	1		T	PT62A	1		T	
VCCIO	VCCIO1	1			VCCIO1	1			
H16	PT52B	1		C	PT61B	1		C	
F16	PT52A	1		T	PT61A	1		T	

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO0	-			GNDIO0	-		
G15	PT41A	0		T	PT46A	0		T
J14	NC	-			PT45B	0		C
L15	NC	-			PT45A	0		T
H14	NC	-			PT44B	0		C
VCCIO	VCCIO0	0			VCCIO0	0		
K14	NC	-			PT44A	0		T
F15	PT38B	0		C	PT42B	0		C
G14	PT38A	0		T	PT42A	0		T
C15	PT37B	0		C	PT41B	0		C
GNDIO	GNDIO0	-			GNDIO0	-		
D14	PT37A	0		T	PT41A	0		T
G13	PT36B	0		C	PT40B	0		C
-	-	-			VCCIO0	0		
J13	PT36A	0		T	PT40A	0		T
B14	PT35B	0		C	PT39B	0		C
VCCIO	VCCIO0	0			-	-		
A14	PT35A	0		T	PT39A	0		T
F13	PT34B	0		C	PT38B	0		C
H13	PT34A	0		T	PT38A	0		T
D13	PT33B	0		C	PT37B	0		C
C14	PT33A	0		T	PT37A	0		T
GNDIO	GNDIO0	-			GNDIO0	-		
E13	PT32B	0		C	PT32B	0		C
D12	PT32A	0		T	PT32A	0		T
G12	PT31B	0		C	PT31B	0		C
E12	PT31A	0		T	PT31A	0		T
VCCIO	VCCIO0	0			VCCIO0	0		
F12	NC	-			PT30B	0		C
D11	NC	-			PT30A	0		T
F11	NC	-			PT29B	0		C
E11	NC	-			PT29A	0		T
D7	ULC_SQ_VCCRX0	11			ULC_SQ_VCCRX0	11		
C9	ULC_SQ_HDINP0	11		T	ULC_SQ_HDINP0	11		T
B9	ULC_SQ_VCCIB0	11			ULC_SQ_VCCIB0	11		
C8	ULC_SQ_HDINN0	11		C	ULC_SQ_HDINN0	11		C
B8	ULC_SQ_VCCTX0	11			ULC_SQ_VCCTX0	11		
A9	ULC_SQ_HDOUTP0	11		T	ULC_SQ_HDOUTP0	11		T
D9	ULC_SQ_VCCOB0	11			ULC_SQ_VCCOB0	11		
A8	ULC_SQ_HDOUTN0	11		C	ULC_SQ_HDOUTN0	11		C
B7	ULC_SQ_VCCTX1	11			ULC_SQ_VCCTX1	11		
A7	ULC_SQ_HDOUTN1	11		C	ULC_SQ_HDOUTN1	11		C
E7	ULC_SQ_VCCOB1	11			ULC_SQ_VCCOB1	11		
A6	ULC_SQ_HDOUTP1	11		T	ULC_SQ_HDOUTP1	11		T
B6	ULC_SQ_VCCRX1	11			ULC_SQ_VCCRX1	11		
C7	ULC_SQ_HDINN1	11		C	ULC_SQ_HDINN1	11		C
D8	ULC_SQ_VCCIB1	11			ULC_SQ_VCCIB1	11		
C6	ULC_SQ_HDINP1	11		T	ULC_SQ_HDINP1	11		T
E6	ULC_SQ_VCCAUX33	11			ULC_SQ_VCCAUX33	11		

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-20E-5Q208I	131	1.2V	-5	PQFP	208	IND	20
LFE2-20E-6Q208I	131	1.2V	-6	PQFP	208	IND	20
LFE2-20E-5F256I	193	1.2V	-5	fpBGA	256	IND	20
LFE2-20E-6F256I	193	1.2V	-6	fpBGA	256	IND	20
LFE2-20E-5F484I	331	1.2V	-5	fpBGA	484	IND	20
LFE2-20E-6F484I	331	1.2V	-6	fpBGA	484	IND	20
LFE2-20E-5F672I	402	1.2V	-5	fpBGA	672	IND	20
LFE2-20E-6F672I	402	1.2V	-6	fpBGA	672	IND	20

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35E-5F484I	331	1.2V	-5	fpBGA	484	IND	35
LFE2-35E-6F484I	331	1.2V	-6	fpBGA	484	IND	35
LFE2-35E-5F672I	450	1.2V	-5	fpBGA	672	IND	35
LFE2-35E-6F672I	450	1.2V	-6	fpBGA	672	IND	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50E-5F484I	339	1.2V	-5	fpBGA	484	IND	50
LFE2-50E-6F484I	339	1.2V	-6	fpBGA	484	IND	50
LFE2-50E-5F672I	500	1.2V	-5	fpBGA	672	IND	50
LFE2-50E-6F672I	500	1.2V	-6	fpBGA	672	IND	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70E-5F672I	500	1.2V	-5	fpBGA	672	IND	70
LFE2-70E-6F672I	500	1.2V	-6	fpBGA	672	IND	70
LFE2-70E-5F900I	583	1.2V	-5	fpBGA	900	IND	70
LFE2-70E-6F900I	583	1.2V	-6	fpBGA	900	IND	70

LatticeECP2 Standard Series Devices, Lead-Free Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6E-5TN144C	90	1.2V	-5	Lead-Free TQFP	144	COM	6
LFE2-6E-6TN144C	90	1.2V	-6	Lead-Free TQFP	144	COM	6
LFE2-6E-7TN144C	90	1.2V	-7	Lead-Free TQFP	144	COM	6
LFE2-6E-5FN256C	190	1.2V	-5	Lead-Free fpBGA	256	COM	6
LFE2-6E-6FN256C	190	1.2V	-6	Lead-Free fpBGA	256	COM	6
LFE2-6E-7FN256C	190	1.2V	-7	Lead-Free fpBGA	256	COM	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12E-5TN144C	93	1.2V	-5	Lead-Free TQFP	144	COM	12
LFE2-12E-6TN144C	93	1.2V	-6	Lead-Free TQFP	144	COM	12
LFE2-12E-7TN144C	93	1.2V	-7	Lead-Free TQFP	144	COM	12
LFE2-12E-5QN208C	131	1.2V	-5	Lead-Free PQFP	208	COM	12
LFE2-12E-6QN208C	131	1.2V	-6	Lead-Free PQFP	208	COM	12
LFE2-12E-7QN208C	131	1.2V	-7	Lead-Free PQFP	208	COM	12
LFE2-12E-5FN256C	193	1.2V	-5	Lead-Free fpBGA	256	COM	12
LFE2-12E-6FN256C	193	1.2V	-6	Lead-Free fpBGA	256	COM	12
LFE2-12E-7FN256C	193	1.2V	-7	Lead-Free fpBGA	256	COM	12
LFE2-12E-5FN484C	297	1.2V	-5	Lead-Free fpBGA	484	COM	12
LFE2-12E-6FN484C	297	1.2V	-6	Lead-Free fpBGA	484	COM	12
LFE2-12E-7FN484C	297	1.2V	-7	Lead-Free fpBGA	484	COM	12

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-20E-5QN208C	131	1.2V	-5	Lead-Free PQFP	208	COM	20
LFE2-20E-6QN208C	131	1.2V	-6	Lead-Free PQFP	208	COM	20
LFE2-20E-7QN208C	131	1.2V	-7	Lead-Free PQFP	208	COM	20
LFE2-20E-5FN256C	193	1.2V	-5	Lead-Free fpBGA	256	COM	20
LFE2-20E-6FN256C	193	1.2V	-6	Lead-Free fpBGA	256	COM	20
LFE2-20E-7FN256C	193	1.2V	-7	Lead-Free fpBGA	256	COM	20
LFE2-20E-5FN484C	331	1.2V	-5	Lead-Free fpBGA	484	COM	20
LFE2-20E-6FN484C	331	1.2V	-6	Lead-Free fpBGA	484	COM	20
LFE2-20E-7FN484C	331	1.2V	-7	Lead-Free fpBGA	484	COM	20
LFE2-20E-5FN672C	402	1.2V	-5	Lead-Free fpBGA	672	COM	20
LFE2-20E-6FN672C	402	1.2V	-6	Lead-Free fpBGA	672	COM	20
LFE2-20E-7FN672C	402	1.2V	-7	Lead-Free fpBGA	672	COM	20